

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	20402	438/618,622,633,637,638,692,552,662,663,672,675,677,698,679,700,704-706,714,725.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 13:46
L2	1243	L1 and ((therm\$4 temperatur\$3 heat\$3) with (decompos\$4 decomposit\$3 destro\$3 wast\$3 consum\$3 absorb\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 16:50
L3	1045	2 and (embed\$3 encav\$3 enclos\$3 cover\$3 recess\$3 buried hollow hole cave)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 13:47
L4	759	2 and ((embed\$3 encav\$3 enclos\$3 cover\$3 recess\$3 buried hollow concave cave hole) with (dielectric insulat\$3 organic \$3oxid\$3 nitrid\$3 interlayer interdielectric interinsulat\$3 (inter adj layer) (inter adj dielectric) (inter adj insulat\$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 16:52
L5	757	4 and (plug contact\$3 \$5connect\$4 \$5conduct\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 13:52
L6	757	4 and (plug \$5contact\$3 \$5connect\$4 \$5conduct\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 16:53
L7	25	(US-20060128089-\$ or US-20050179135-\$ or US-20050124168-\$ or US-20050151256-\$ or US-20050272248-\$ or US-20030205817-\$ or US-20050042874-\$ or US-20050079705-\$ or US-20040099951-\$).did. or (US-6821896-\$ or US-6440842-\$ or US-6174804-\$ or US-6033977-\$ or US-6309957-\$ or US-6803669-\$ or US-6949456-\$ or US-6358849-\$ or US-6596624-\$ or US-7211496-\$ or US-6171971-\$ or US-6898851-\$ or US-6800551-\$ or US-6664181-\$ or US-6514671-\$ or US-6440838-\$).did.	US-PGPUB; USPAT	OR	ON	2007/09/27 14:53
L8	673	6 and ((remov\$3 etch\$3) with (dielectric insulat\$3 organic \$3oxid\$3 nitrid\$3 interlayer interdielectric interinsulat\$3 (inter adj layer) (inter adj dielectric) (inter adj insulat\$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 15:45
L9	518	8 and ((embed\$3 encav\$3 enclos\$3 cover\$3 recess\$3 buried hollow concave cave hole) near3 (dielectric insulat\$3 organic \$3oxid\$3 nitrid\$3 interlayer interdielectric interinsulat\$3 (inter adj layer) (inter adj dielectric) (inter adj insulat\$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 15:01
L10	86	9 and project\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 15:03
L11	2	9 and (trip\$3 near2 shape\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 15:03
L12	247	9 and (dielectric insulat\$3 \$5mask\$5 sacrificial\$3) near2 (region portion)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 15:05

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L13	13	("20020028575" "20020098677" "20030064577" "20040063305" "20050037604" "5798559" "6255712" "6440838" "6440861" "6780753" "6815329" "6841844").PN. OR ("6949456").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/27 15:10
L14	7	("6033977" "6174804" "6284641" "6309957").PN. OR ("6440842").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/27 15:23
L15	72	("4523372" "5158910" "5422309" "5529953" "5602423" "5614765" "5705430" "5710061" "5801099").PN. OR ("6033977").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/27 15:28
L16	190	12 not (7 10 11 13 14 15)	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/27 16:06
L19	180	16 and ((remov\$3 etch\$3) near4 (dielectric insulat\$3 organic \$3oxid\$3 nitrid\$3 interlayer interdielectric interinsulat\$3 (inter adj layer) (inter adj dielectric) (inter adj insulat\$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 16:55
L20	1570	438/618.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 15:59
L21	3056	438/637.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 15:47
L22	10	12 not (7 10 11 13 14 15 19)	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/27 16:54
L23	763	438/666.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/27 16:49
L24	3308	257/e21.579.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 16:44
L25	26856	((therm\$4 temperatur\$3 heat\$3) near3 (decompos\$4 decompisit\$3 destro\$3 wast\$3 consum\$3 absorb\$3)) and ((embed\$3 encav\$3 enclos\$3 cover\$3 recess\$3 buried hollow concave cave hole) near4 (dielectric insulat\$3 organic \$3oxid\$3 nitrid\$3 interlayer interdielectric interinsulat\$3 (inter adj layer) (inter adj dielectric) (inter adj insulat\$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 16:58
L26	25358	25 and (plug \$5contact\$3 \$5connect\$4 \$5conduct\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 17:57
L27	24848	26 not (7 10 11 13 14 15 19 22)	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/27 16:55
L28	8303	27 and ((therm\$4 temperatur\$3 heat\$3) with (decompos\$4 decompisit\$3 destro\$3 wast\$3 consum\$3 absorb\$3) with (dielectric insulat\$3 organic \$3oxid\$3 nitrid\$3 interlayer interdielectric interinsulat\$3 (inter adj layer) (inter adj dielectric) (inter adj insulat\$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 16:57
L29	4147	28 and ((therm\$4 temperatur\$3 heat\$3) with (decompos\$4 decompisit\$3) with (dielectric insulat\$3 organic \$3oxid\$3 nitrid\$3 interlayer interdielectric interinsulat\$3 (inter adj layer) (inter adj dielectric) (inter adj insulat\$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 18:01

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L30	670	29 and project\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 17:02
L31	4043	29 and ((therm\$4 temperatur\$3 heat\$3) near3 (decompos\$4 decomposit\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 17:03
L32	642	30 and 31	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 17:04
L33	556	32 and (@ad<"20050612" @rlad<"20050615")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 17:04
L34	325	33 and ((plug \$5contact\$3 \$5connect\$4 \$5conduct\$3) near4 (hole trench open\$3 via strip\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 17:09
L35	4649	((plug \$5contact\$3 \$5connect\$4 \$5conduct\$3) and ((therm\$4 temperatur\$3 heat\$3) near3 (decompos\$4 decomposit\$3))). clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 18:00
L36	475	35 and ((remov\$3 etch\$3) near5 (thermal\$3 thermo\$4 heat\$3 temperat\$3)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 17:59
L37	169	36 and (\$4silicon semiconduct\$3).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 18:00
L38	38	37 and (((therm\$4 temperatur\$3 heat\$3) with (decompos\$4 decomposit\$3) with (dielectric insulat\$3 organic \$3oxid\$3 nitrid\$3 interlayer interdielectric interinsulat\$3 (inter adj layer) (inter adj dielectric) (inter adj insulat\$3))))).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 18:02

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Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	55	"6033977"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/30 15:18
S2	44	S1 and ((dielectric insulat\$4 organic \$2oxide) same (via recess open\$3 groov\$3 trench\$3 gap\$3 slot\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 15:10
S3	43	S2 and (remov\$4 heat\$4 temperatur\$4 therm\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/25 16:31
S4	1	10/539280	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/25 16:31
S5	4	("6033977" "6174804" "6284641" "6309957").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/25 16:37
S6	49	("5766446" "5475567" "5508881" "5625528" "5741721" "5889449" "6128178" "4266263" "4370697" "4373782" "4828346" "4837534" "4870319" "5012319" "5200855" "5381149" "5471221" "5472886" "5488199" "5742002" "5748358" "5893967" "5909261" "5936493" "5978157").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 14:01
S7	5	S6 and ((organic \$2oxide \$nitride) same (remov\$4 burn\$4 melt\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 12:12
S8	7	S6 and ((organic \$2oxide \$nitride) same (heat\$4 temperatur\$4 therm\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 12:19
S9	3	Hoang-viet-nguyen.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 14:04
S10	9	Nguyen-hoang-viet.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 14:09
S11	7	gravesteijn-dirk-jan.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 14:05

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S12	1	hoofman-romano-julma-oscar-maria.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 14:03
S13	0	Nguyen-viet-hoang.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 14:04
S14	2729	438/637.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 15:02
S15	2792	438/622.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 14:49
S16	14538	257/296,741,750,774,e21.553,e21.579,e21.585,e21.587,e21.589,e23.145.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 15:04
S17	831	H01L21/4763.ipc.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 15:05
S18	774	H01L21/302.ipc.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 15:06
S19	1996	(S16 S17 S18) and (organic same (heat\$4 therm\$4 temperatur\$4 melt\$4 vapor\$6 evaporat\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 15:11
S20	1808	S19 and ((dielectric insulat\$4 organic \$2oxide) same (via recess open\$3 groov\$3 trench\$3 gap\$3 slot\$3 plug))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 15:10
S21	1535	S20 and (organic same (temperatur\$4 melt\$4 vapor\$6 evaporat\$4 decompos\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 15:12
S22	880	S21 and (organic with (temperatur\$4 melt\$4 vapor\$6 evaporat\$4 decompos\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 15:16

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S23	421	S21 and (organic with (temperatur\$4 melt\$4 vapor\$6 evaporat\$4 decompos\$4) with (larg\$3 high\$4 low\$4 small\$3 above below))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 15:14
S24	280	S23 and (organic with (temperatur\$4 heat\$4 therm\$4) with (larg\$3 high\$4 low\$4 small\$3 above below))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 15:14
S25	100	S24 and (organic with (temperatur\$4 heat\$4 therm\$4) with (melt\$4 vapor\$6 evaporat\$4 decompos\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 16:17
S26	55	S24 and (organic with (temperatur\$4 heat\$4 therm\$4) with (remov\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 16:34
S27	78	S25 not S26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 16:20
S28	89	S22 and (organic with (temperatur\$4 heat\$4 therm\$4) with (remov\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 16:36
S29	34	S28 not S26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 16:58
S30	7	("6033977" "6174804" "6284641" "6309957").PN. OR ("6440842").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/28 20:34
S31	21	("5512514" "5691238" "5693568" "5705430" "5795823" "5981374" "6187663").PN. OR ("6309957").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/28 20:35
S32	13	("20020028575" "20020098677" "20030064577" "20040063305" "20050037604" "5798559" "6255712" "6440838" "6440861" "6780753" "6815329" "6841844").PN. OR ("6949456").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/28 20:37
S33	67	("4523372" "5158910" "5422309" "5529953" "5602423" "5614765" "5705430" "5710061" "5801099").PN. OR ("6033977").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/28 20:43
S34	3956	((dielectric insulat\$3) with organic) and (decomposit\$3 with (thermal\$3 heat\$3 temperatur\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 15:20
S35	1772	S34 and ((dielectric insulat\$3 organic) with (decomposit\$3 with (thermal\$3 heat\$3 temperatur\$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 15:25

EAST Search History

S36	1449	S35 and (@ad<"20021220" @rlad<"20021220" @pd<"20040615" @rlpd<"20040615")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 18:40
S37	780	S36 and (trench recess\$3 groov\$3 open\$3 plug)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 19:15
S38	418	S37 and semiconduct\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 15:22
S39	18	(US-20060128089-\$ or US-20050179135-\$ or US-20050124168-\$ or US-20050151256-\$ or US-20050079705-\$).did. or (US-6309957-\$ or US-6821896-\$ or US-6174804-\$ or US-6033977-\$ or US-6440842-\$ or US-6949456-\$ or US-6358849-\$ or US-6803669-\$ or US-6898851-\$ or US-6800551-\$ or US-6664181-\$ or US-6440838-\$ or US-6514671-\$).did.	US-PGPUB; USPAT	OR	ON	2007/05/30 15:22
S40	415	S38 not S39	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 15:23
S41	219	S40 and (photoresist \$4resist photomask photo-resist photo-mask)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 15:23
S42	212	S41 and (trench recess\$3 groov\$3 open\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 15:24
S43	200	S42 and (decomposit\$3 near5 (thermal\$3 heat\$3 temperatur\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 15:25
S44	212	S42 and ((organic dielectric insulat\$3) with decomposit\$3 with (thermal\$3 heat\$3 temperatur\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 15:26
S45	200	S43 and ((organic dielectric insulat\$3) with decomposit\$3 with (thermal\$3 heat\$3 temperatur\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 15:27
S46	198	S45 and (substrate wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 15:27
S47	135	S46 and liquid	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 15:27
S48	92	S47 and (solid\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 18:39

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S49	92	(US-20020189495-\$ or US-20030196680-\$ or US-20040163758-\$ or US-20070102685-\$ or US-20070102684-\$ or US-20070102683-\$ or US-20070102682-\$ or US-20070102681-\$ or US-20070102680-\$ or US-20070102679-\$ or US-20070102678-\$ or US-20070102677-\$ or US-20070096065-\$ or US-20070096064-\$ or US-20070096063-\$ or US-20070096062-\$ or US-20060043346-\$ or US-20030205817-\$ or US-20040169287-\$ or US-20010026021-\$ or US-20070019028-\$ or US-20050057908-\$ or US-20030147227-\$ or US-20050129383-\$ or US-20050047927-\$ or US-20030198578-\$).did. or (US-20030180451-\$ or US-20030148024-\$ or US-20030108664-\$ or US-20070104870-\$ or US-20070104869-\$ or US-20070104882-\$ or US-20070104881-\$ or US-20070104880-\$ or US-20070104879-\$ or US-20070104876-\$ or US-20070104875-\$ or US-20070104883-\$ or US-20030124259-\$ or US-20030087036-\$ or US-20030175411-\$ or US-20020018845-\$ or US-20020176927-\$ or US-20030099844-\$ or US-20020102501-\$ or US-20070117271-\$ or US-20030092213-\$ or US-20050272248-\$ or US-20040102031-\$ or US-20050032357-\$ or US-20070099330-\$ or US-20050255710-\$ or US-20030004218-\$).did. or (US-5534069-\$ or US-6113730-\$ or US-5686172-\$ or US-6046410-\$ or US-5393406-\$ or US-5622634-\$ or US-6072207-\$ or US-6492659-\$ or US-5900674-\$ or US-6734566-\$ or US-6298551-\$ or US-6826830-\$ or US-6366015-\$ or US-7122152-\$ or US-5547708-\$ or US-6951666-\$ or US-6800330-\$ or US-6787191-\$ or US-6946159-\$ or US-6506440-\$ or US-6296896-\$ or US-6998148-\$ or US-6685983-\$ or US-6887332-\$ or US-6379745-\$ or US-5830548-\$).did. or (US-6338936-\$ or US-6576409-\$ or US-6077635-\$ or US-7074650-\$ or US-6762081-\$ or US-6596624-\$ or US-5953634-\$ or US-6156657-\$ or US-6602804-\$ or US-5602060-\$ or US-6334803-\$ or US-6420441-\$ or US-6232386-\$).did.	US-PGPUB; USPAT	OR	ON	2007/05/30 18:39
S50	1	((thermal near2 decompost\$4) with (polymer\$3 polyimide)) and (insulat\$4 dielectric) and (@ad<"20021220" @rlad<"20021220" @pd<"20040615" @rlpd<"20040615")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 18:41
S51	21	(US-20060128089-\$ or US-20050179135-\$ or US-20050124168-\$ or US-20050151256-\$ or US-20050079705-\$ or US-20050272248-\$ or US-20030205817-\$).did. or (US-6309957-\$ or US-6821896-\$ or US-6174804-\$ or US-6033977-\$ or US-6440842-\$ or US-6949456-\$ or US-6358849-\$ or US-6803669-\$ or US-6898851-\$ or US-6800551-\$ or US-6664181-\$ or US-6440838-\$ or US-6514671-\$ or US-6596624-\$).did.	US-PGPUB; USPAT	OR	ON	2007/05/30 18:40
S52	1	((thermal\$3 near2 decompost\$4) with (polymer\$3 polyimide)) and (insulat\$4 dielectric) and (@ad<"20021220" @rlad<"20021220" @pd<"20040615" @rlpd<"20040615")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 18:42
S53	7	((thermal\$3 near2 decompost\$4) with (polymer\$3 polyimide)) and (@ad<"20021220" @rlad<"20021220" @pd<"20040615" @rlpd<"20040615")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 18:42
S54	11	((thermal\$3 near2 decompost\$4) same (polymer\$3 polyimide)) and (@ad<"20021220" @rlad<"20021220" @pd<"20040615" @rlpd<"20040615")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 18:44

EAST Search History

S55	56	((thermal\$3 near2 decompost\$4)) and (@ad<"20021220" @rlad<"20021220" @pd<"20040615" @rlpd<"20040615")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 18:46
S56	45	S55 not (S49 S51 S54)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 18:47
S57	25	S56 and organic	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 18:44
S58	140	((((temperat\$4 heat\$3 thermal\$3) near4 decompost\$4)) and (@ad<"20021220" @rlad<"20021220" @pd<"20040615" @rlpd<"20040615")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 18:51
S59	0	S58 not (S49 S51 S54 S58)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 18:47
S60	104	S58 not (S49 S51 S54 S57)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 18:51
S61	44	S60 and organic	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 18:47
S62	23218	(organic with decomposit\$4) and (@ad<"20021220" @rlad<"20021220" @pd<"20040615" @rlpd<"20040615")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 19:09
S63	23128	S62 not (S49 S51 S54 S57 S58)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 18:51
S64	5715	S63 and (insulat\$4 dielectric)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 19:09
S65	2	S64 and ((temperat\$4 heat\$3 thermal\$3) with decompost\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 19:11
S66	10	S64 and ((temperat\$4 heat\$3 thermal\$3) same decompost\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 18:58
S67	1	("6141072").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/05/30 18:59

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S68	1	("6165890").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/05/30 19:00
S69	1	("7141885").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/05/30 19:08
S70	12607	(organic and (remov\$4 with decompos\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 19:14
S71	10992	(S70 not (S49 S51 S54 S57 S58 S66)) and (@ad<"20021220" @rlad<"20021220" @pd<"20040615" @rlpd<"20040615")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 19:09
S72	930	S71 and (insulat\$4 dielectric) and semiconduct\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 19:09
S74	375	S72 and ((temperat\$4 heat\$3 thermal\$3) with decomposit\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 19:10
S75	3884	S64 and ((temperat\$4 heat\$3 thermal\$3) with decomposit\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 19:12
S76	3102	(S74 S75) and ((temperat\$4 heat\$3 thermal\$3) with decomposit\$4 with organic)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 19:13
S77	973	S76 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 19:13
S78	78	S77 and (remov\$4 with decompos\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 19:14
S79	147	S77 and (remov\$4 with decomposit\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 19:14
S80	98	S79 and (trench recess\$3 groov\$3 open\$3 plug)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/26 22:42
S81	91	S80 and (substrate wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/05/30 19:16

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S82	20381	438/618,622,633,637,638,692,552,662,663,672,675,677,698,679,700,704-706,714,725.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/26 19:11
S83	910	S82 and ((therm\$4 temperatur\$3 heat\$3) with (decompo\$4 destro\$3 wast\$3 consum\$3 absorb\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/26 19:30
S84	673	S83 and (embed\$3 encav\$3 enclos\$3 cover\$3 recess\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/26 19:31
S85	427	S83 and (embed\$3 encav\$3 enclos\$3 cover\$3 recess\$3) with (dielectric insulat\$3 organic \$3oxid\$3 nitrid\$3 interlayer interdielectric interinsulat\$3 (inter adj layer) (inter adj dielectric) (inter adj insulat\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/26 19:31
S86	274	S85 and ((therm\$4 temperatur\$3 heat\$3) with (remov\$3 wast\$3 etch\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/26 19:32
S87	152	S86 and ((therm\$4 temperatur\$3 heat\$3) near\$3 (decompo\$4 destro\$3 wast\$3 consum\$3 absorb\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/26 19:22
S88	9	S87 and ((therm\$4 temperatur\$3 heat\$3) near\$3 (decompo\$4 destro\$3 wast\$3 consum\$3 absorb\$3)).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/26 19:24
S89	0	S87 and ((therm\$4 temperatur\$3 heat\$3) near\$3 (decompo\$4 destro\$3 wast\$3 consum\$3 absorb\$3)).ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/26 19:25
S90	22	S87 and ((therm\$4 temperatur\$3 heat\$3) near\$3 (decompo\$4 destro\$3 wast\$3 consum\$3 absorb\$3)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/26 19:29
S91	129	S87 not (S88 S90)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/26 19:33
S92	1237	S82 and ((therm\$4 temperatur\$3 heat\$3) with (decompo\$4 decomposit\$3 destro\$3 wast\$3 consum\$3 absorb\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/26 19:48
S93	958	S92 and (embed\$3 encav\$3 enclos\$3 cover\$3 recess\$3 buried)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 13:46
S94	616	S93 and (embed\$3 encav\$3 enclos\$3 cover\$3 recess\$3 buried) with (dielectric insulat\$3 organic \$3oxid\$3 nitrid\$3 interlayer interdielectric interinsulat\$3 (inter adj layer) (inter adj dielectric) (inter adj insulat\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 13:49

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S95	385	S94 and ((therm\$4 temperatur\$3 heat\$3) with (remov\$3 wast\$3 etch\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/26 19:33
S96	362	(S91 S95) not (S88 S90)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/26 19:33
S97	1243	S82 and ((therm\$4 temperatur\$3 heat\$3) with (decompos\$4 decomposit\$3 destro\$3 wast\$3 consum\$3 absorb\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/27 13:46
S98	368	(S97 not S92) S96	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/26 19:53